

Description

The IRF7413TRPBF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 30V I_D =8.5A

 $R_{DS(ON)}$ < 18m Ω @ V_{GS}=10V

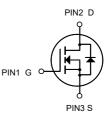
Application

Battery protection

Load switch Uninterruptible power supply







N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
IRF7413TRPBF	SOP-8	F7413 XXXX	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	meter Rating	
Vds	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
I₀@T _A =25°C	Continuous Drain Current ¹	8.5	А
I _D @T _A =70°C	Continuous Drain Current ¹	5.6	А
Ідм	Pulsed Drain Current ²	35	А
EAS	Single Pulse Avalanche Energy ³	20	mJ
las	Avalanche Current	20	А
P _D @T _A =25°C	Total Power Dissipation ⁴	1.5	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
	Thermal Resistance Junction-ambient ¹ (t≤10s)	85	°C/W
R _θ ja	Thermal Resistance Junction-ambient ¹	25	°C/W



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
$\triangle BV_DSS / \triangle$	BVDSS Temperature Coefficient	Reference to 25°C,I₀=1mA		0.034		V/°C	
D 04-4	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =7A	14.5 18 20 26		18	mΩ	
R _{DS(ON)}	Static Drain-Source On-Resistance-	V _{GS} =4.5V , I _D =4A			26		
V _{GS(th)}	Gate Threshold Voltage		1.2	1.5	2.5	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	──V _{GS} =V _{DS} , I _D =250uA		-3.84		mV/°C	
1	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1		
loss		V _{DS} =24V , V _{GS} =0V , T _J =55°C	, T _J =55°C 5		5	– uA	
lgss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =7A		6.2		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.04	2.1	Ω	
Qg	Total Gate Charge (4.5V)			6	8.4		
Q_gs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =7A		2.2	3.1	nC	
Q_{gd}	Gate-Drain Charge			2	2.8		
T _{d(on)}	Turn-On Delay Time			1.2	2.4		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_G =3.3 Ω		40	72.0	- ns	
T _{d(off)}	Turn-Off Delay Time	I _D =7A		18	36.0		
T _f	Fall Time			7.2	14.4		
Ciss	Input Capacitance			583	816.2		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		77	107.8	pF	
C _{rss}	Reverse Transfer Capacitance			59	82.6		
Is	Continuous Source Current ^{1,5}				7	А	
I _{SM}	Pulsed Source Current ^{2,5}	──V _G =V _D =0V , Force Current			35	А	
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	
trr	Reverse Recovery Time			7.2		nS	
Qrr	Reverse Recovery Charge	IF=7A , dl/dt=100A/μs , Tյ=25°C		2.9		nC	

Electrical Characteristics (TJ=25 °C, unless otherwise noted)

Note :

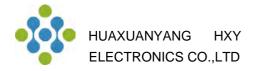
1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}25V, V_{\text{GS}}\text{=}10V, L\text{=}0.1\text{mH}, I_{\text{AS}}\text{=}20\text{A}$

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



IRF7413TRPBF N-Channel Enhancement Mode MOSFET

Typical Characteristics

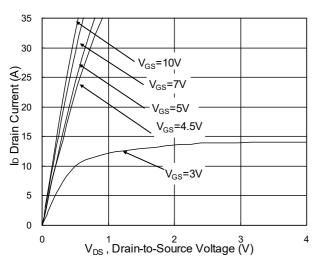


Fig.1 Typical Output Characteristics

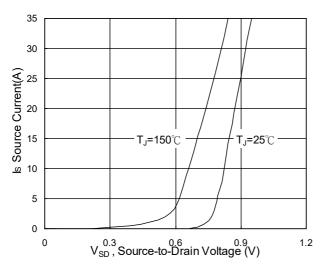


Fig.3 Forward Characteristics Of Reverse

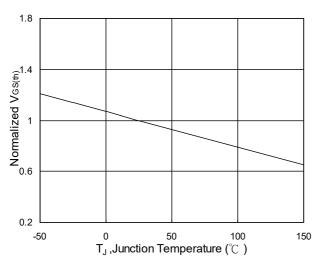


Fig.5 Normalized $V_{\text{GS}(\text{th})}$ vs. T_J

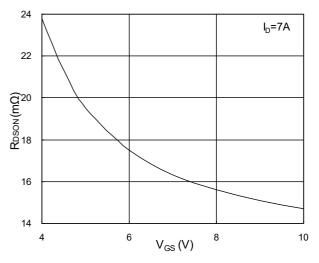


Fig.2 On-Resistance vs. Gate-Source

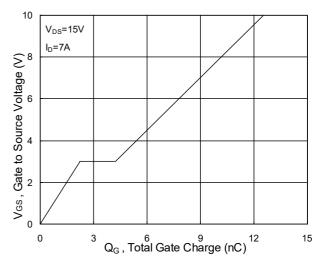


Fig.4 Gate-Charge Characteristics

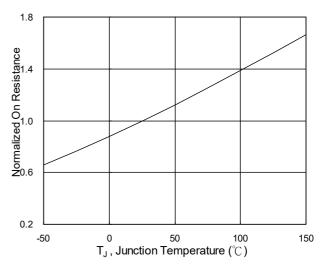


Fig.6 Normalized R_{DSON} vs. T_J



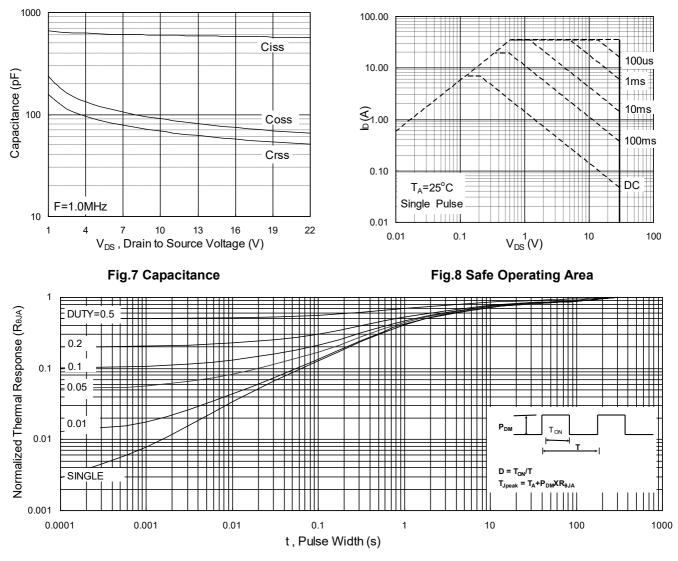


Fig.9 Normalized Maximum Transient Thermal Impedance

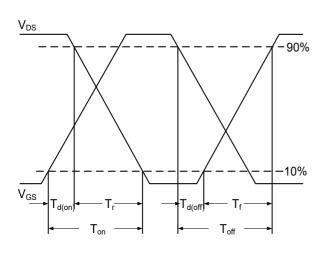


Fig.10 Switching Time Waveform

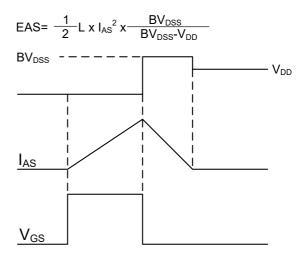
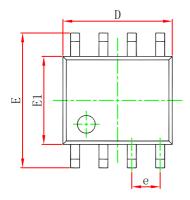
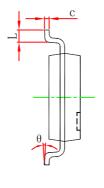


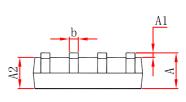
Fig.11 Unclamped Inductive Switching Waveform



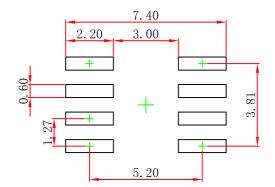
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0 °	8°	0 °	8°	



- Note: 1.Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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